## AMENDMENTS TO THE CLAIMS

*Claim 1. (Canceled)*

2. (Currently amended) A substrate plating apparatus for electrolessly plating a surface of a semiconductor substrate with metal, said apparatus comprising:

a plating area including at least one plating chamber for containing a plating solution for electrolessly plating a semiconductor substrate with metal;

a cleaning and drying area including at least one cleaning unit comprising a cleaner with a sponge layer for cleaning a plated semiconductor substrate; ~~and~~

a partition disposed between said plating area and said cleaning and drying area;;

a concentration analyzing device to analyze concentrations of components of the plating solution; and

a plating solution preparing device to prepare the plating solution based on the concentration as analyzed by said concentration analyzing device;

wherein pressure in said cleaning and drying area is greater than pressure in said plating area.

*3. (Canceled)*

4. (Previously presented) The substrate plating apparatus according to claim ~~3~~ 2, wherein

said concentration analyzing device includes a metal ion concentration analyzer and a plating additive concentration analyzer.

*5. (Canceled)*

6. (Previously presented) The substrate plating apparatus according to claim ~~5~~ 4, further comprising:

a loading and unloading area, wherein said cleaning and drying area is disposed between said loading and unloading area and said plating area.

*7. (Canceled)*

8. (Previously presented) The substrate plating apparatus according to claim ~~7~~ 6, further comprising:

a chemical mechanical polishing unit.

9. (Previously presented) The substrate plating apparatus according to claim 8, wherein

said plating area includes at least one pretreatment chamber.

*10. (Canceled)*

11. (Previously presented) The substrate plating apparatus according to claim ~~10~~ 9, wherein

said cleaner is a pencil-shaped cleaner or a roller.

12. (Previously presented) The substrate plating apparatus according to claim 11, wherein

air is to flow downwardly in said plating area.

13. (Previously presented) The substrate plating apparatus according to claim 12, wherein

air is to flow downwardly in said cleaning and drying area.

*14 and 15. (Canceled)*

16. (Previously presented) The substrate plating apparatus according to claim 2, wherein

said plating area includes at least one pretreatment chamber.

17. (Previously presented) The substrate plating apparatus according to claim 2, further comprising:

a loading and unloading area, wherein said cleaning and drying area is disposed between said loading and unloading area and said plating area.

18. (Previously presented) The substrate plating apparatus according to claim 2, wherein

said cleaner is a pencil-shaped cleaner or a roller.

19. (Previously presented) The substrate plating apparatus according to claim 2, further comprising:

a chemical mechanical polishing unit.

20. (Previously presented) The substrate plating apparatus according to claim 2, wherein

air is to flow downwardly in said plating area.

21. (Previously presented) The substrate plating apparatus according to claim 2, wherein

air is to flow downwardly in said cleaning and drying area.

22. (New) The substrate plating apparatus according to claim 4, wherein

said plating area includes at least one pretreatment chamber.

23. (New) The substrate plating apparatus according to claim 4, wherein said cleaner is a pencil-shaped cleaner or a roller.

24. (New) The substrate plating apparatus according to claim 4, further comprising: a chemical mechanical polishing unit.

25. (New) The substrate plating apparatus according to claim 4, wherein air is to flow downwardly in said plating area.

26. (New) The substrate plating apparatus according to claim 4, wherein air is to flow downwardly in said cleaning and drying area.